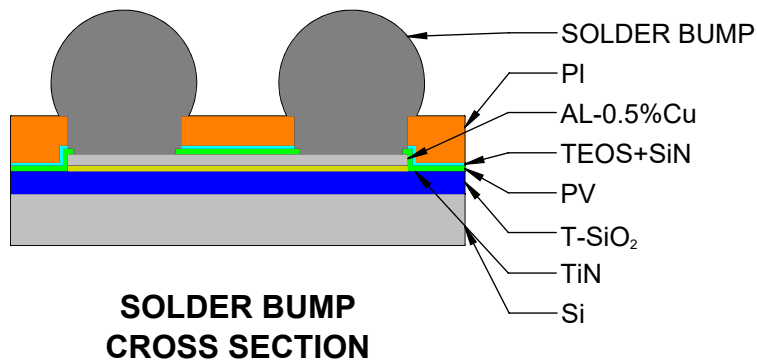


BUMP VIEW

**SECTION E-E
SCALE 8 : 1**

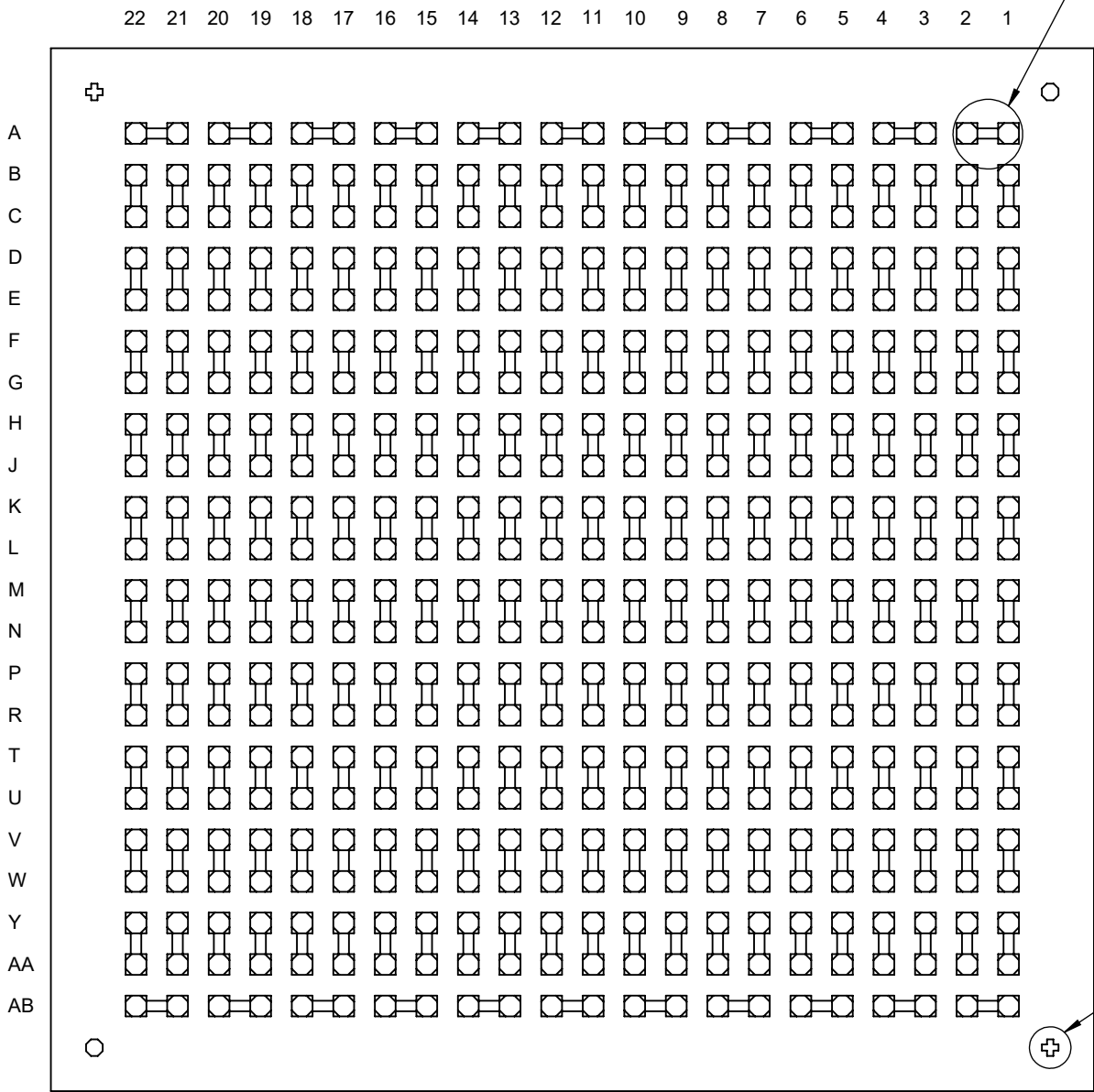
NOTES: (UNLES OTHERWISE SPECIFIED)

- 1) DIMENSIONS: μm (MICRON).
- 2) WAFER SIZE: $\phi 200$ mm (8-INCH).
- 3) BUMP ALLOY: SAC305.
- 4) BUMP HEIGHT: $74\mu\text{m}$.
- 5) BUMP DIAMETER: $109\mu\text{m}$.

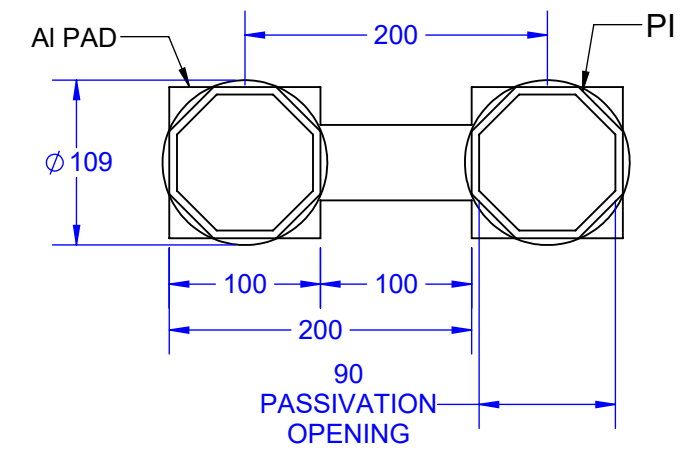


TopLine®			
TITLE FC4356G15C200-DC DAISY CHAIN BUMPED DIE			
SCALE 12:1	SIZE A	DRAWING NO. 174356	REV A
DO NOT SCALE DRAWING			SHEET 1 OF 7

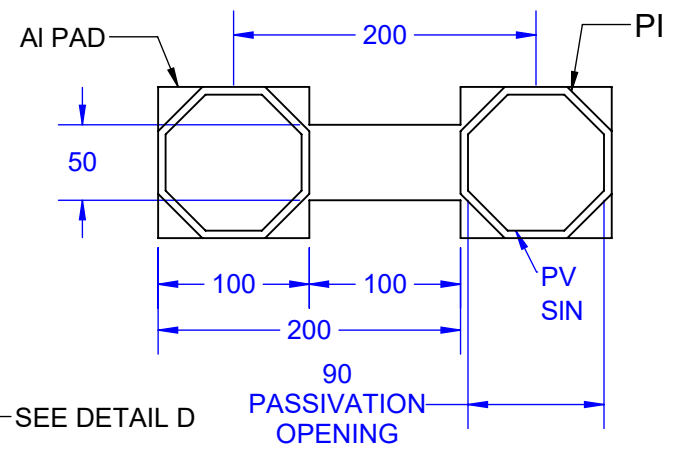
DETAIL B



DETAIL C SOLDER BUMP PAD SCALE = 200:1



PASSIVATION OPENING SCALE = 200:1

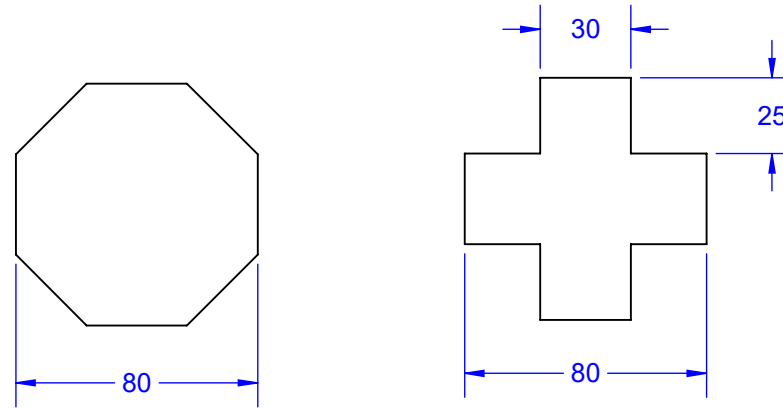


NOTES: (UNLES OTHERWISE SPECIFIED)

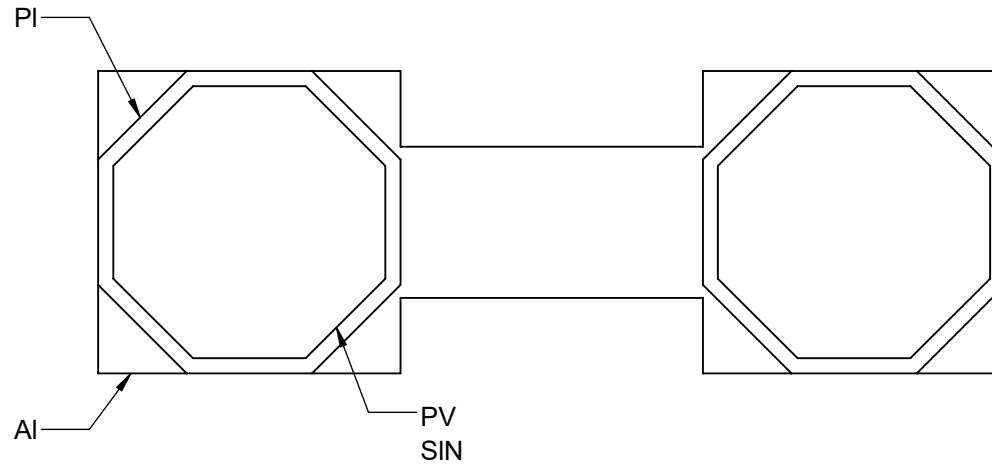
- 1) DIMENSIONS: μm (MICRON).
- 2) FC4356 = 9X FC484 (SEE DETAIL A).

TopLine			
TITLE FC4356G15C200-DC DAISY CHAIN BUMPED DIE			
SCALE 30:1	SIZE A	DRAWING NO. 174356	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 7

DETAIL "D" FIDUCIAL



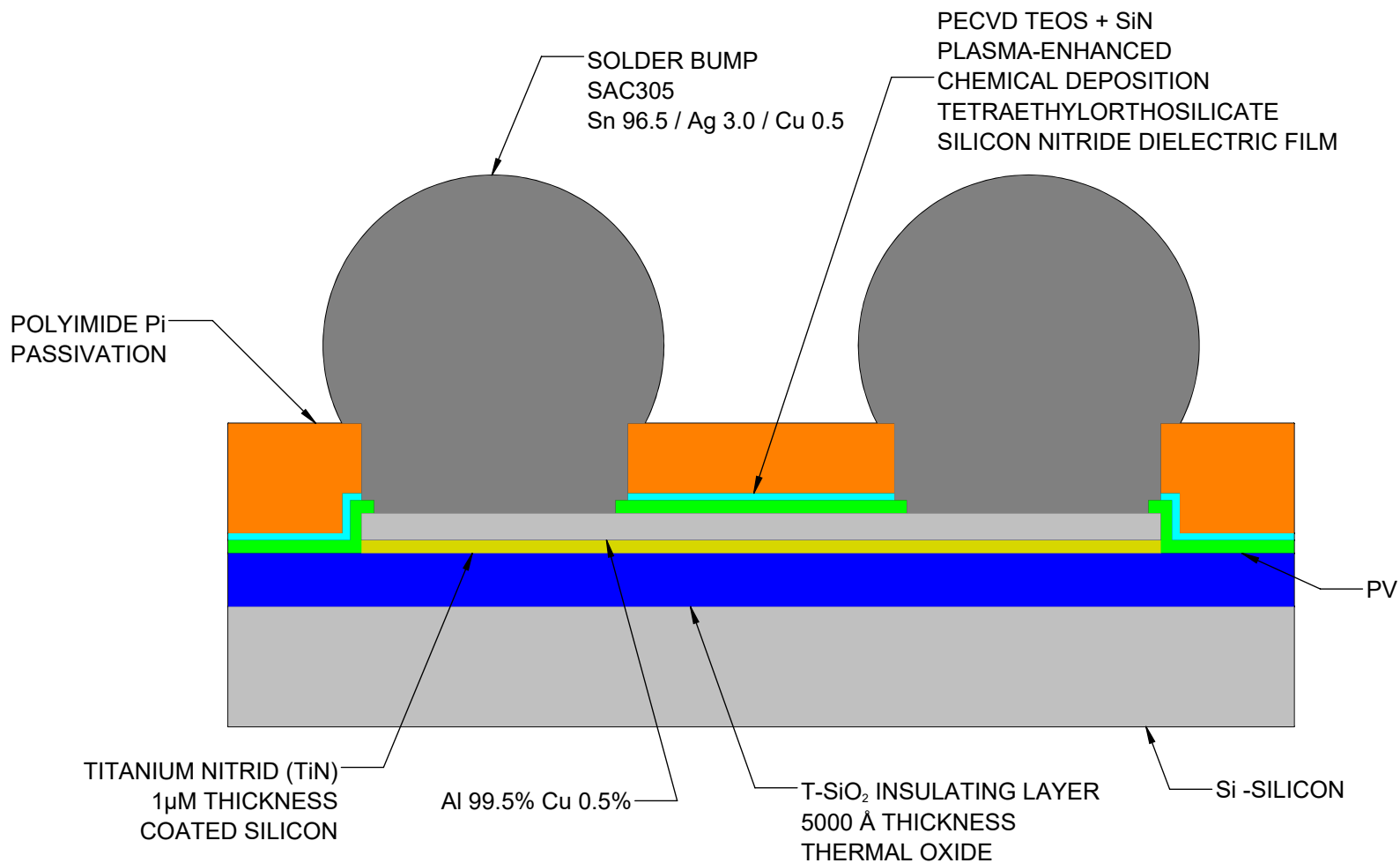
UBM PAD DETAIL



NOTES: (UNLES OTHERWISE SPECIFIED)
1) DIMENSIONS: μm (MICRON).

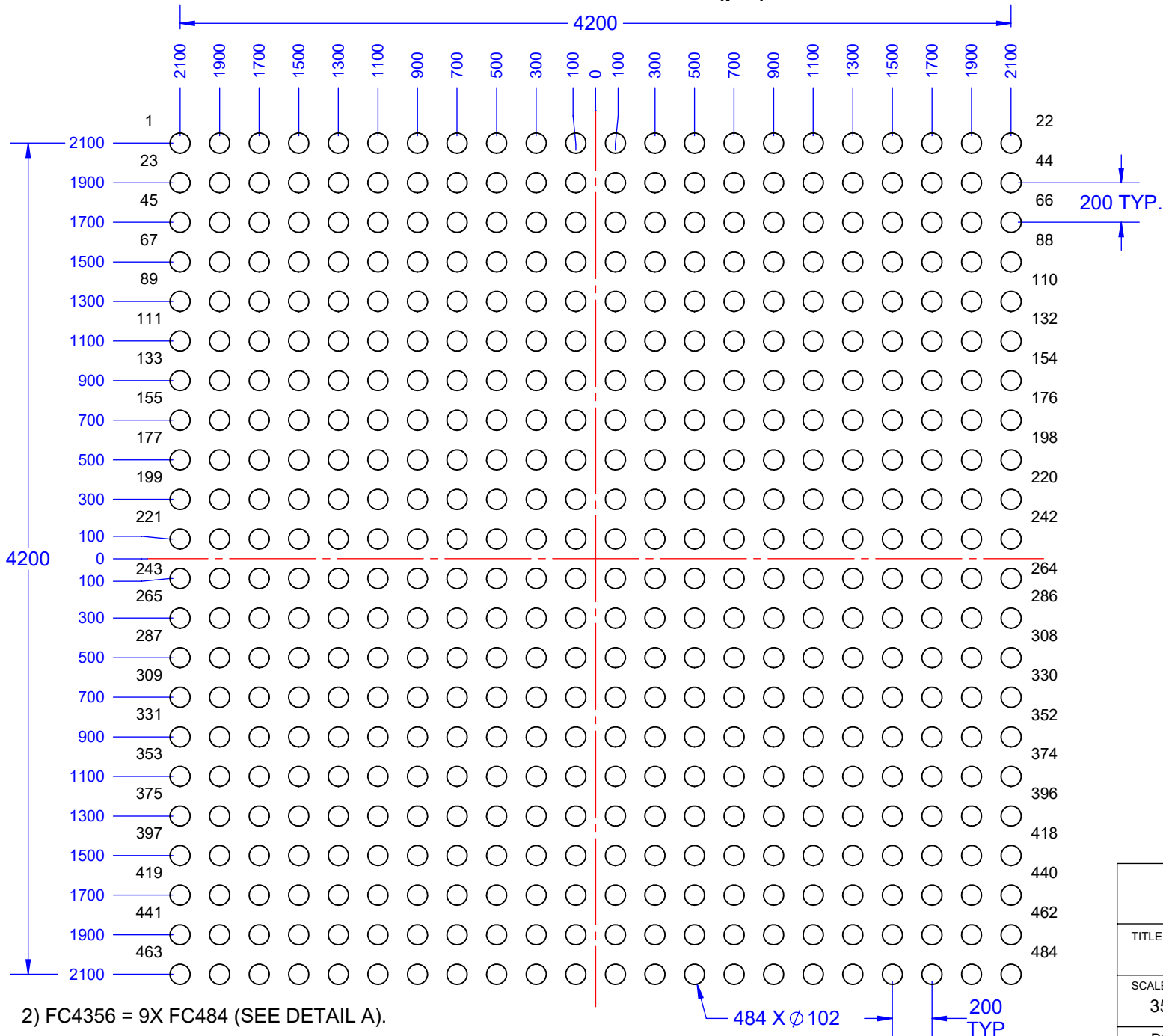
TopLine [®]			
TITLE FC4356G15C200-DC DAISY CHAIN BUMPED DIE			
SCALE 400:1	SIZE A	DRAWING NO. 174356	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 7	

DIMENSIONS μm



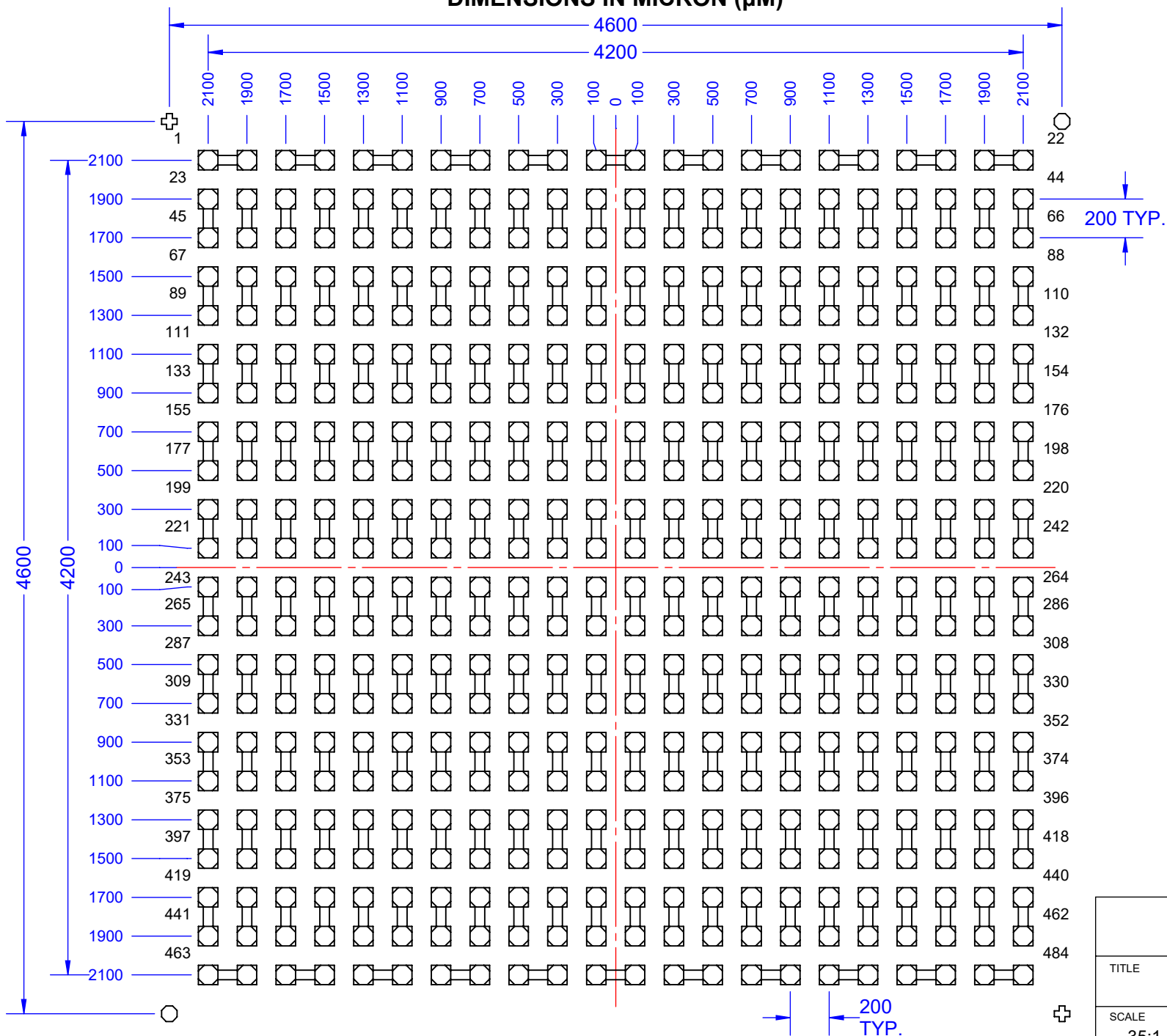
TopLine[®]			
TITLE FC4356G15C200-DC DAISY CHAIN BUMPED DIE			
SCALE 400:1	SIZE A	DRAWING NO. 174356	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 7

**PAD LOCATION
SHOWN BUMP VIEW
DIMENSIONS IN MICRON (μM)**



TopLine[®]			
TITLE FC4356G15C200-DC DAISY CHAIN BUMPED DIE			
SCALE 35:1	SIZE A	DRAWING NO. 174356	REV A
DO NOT SCALE DRAWING		SHEET 5 OF 7	

**PAD LOCATION
DIMENSIONS IN MICRON (μM)**



2) FC4356 = 9X FC484 (SEE DETAIL A)

TopLine®			
TITLE FC4356G15C200-DC DAISY CHAIN BUMPED DIE			
SCALE 35:1	SIZE A	DRAWING NO. 174356	REV A
DO NOT SCALE DRAWING		SHEET 6 OF 7	

PART NUMBERING SYSTEM

FC

4356

G

15

C

200

- OPTION -

DC

- PACKAGING

FLIP CHIP

FC = STANDARD FLIP CHIP
 FCW = BUMPED WAFER*
 FCN = BUMPLESS CHIP
 FCWN = BUMPLESS WAFER*

*200MM WAFER

NUMBER OF BUMPS

BUMP	CHIPS
484	1X
1936	4X
2904	6X
4356	9X
7744	16X

BUMP DIAMETER

DIAMETER ϕ 109 μ m
 HEIGHT 74 μ m

DIE SIZE

BUMP	SIZE
484	5 x 5 mm
1936	10 x 10 mm
2904	10 x 15 mm
4356	15 x 15 mm
7744	20 x 20 mm

PAD MATERIAL

C = SAC BUMP
 A = AI PAD (BUMPESS)
 G = GOLD PAD (BUMPLESS)

BUMP PITCH

μ M

DIE THINNING

CODE	μ M	MIL
NONE	500	20
BG400	400	16
BG350	350	14
BG300	300	12
BG250	250	10
BG200	200	8

OTHER THICKNESS
 AVAILABLE

DAISY CHAIN

OPTIONS

BLANK = TRAY (STANDARD)

BUMP	TRAY	QTY
484	2-INCH	36 PCS
1936	4-INCH	49 PCS
2904	4-INCH	24 PCS
4356	4-INCH	25 PCS
7744	4-INCH	9 PCS

WAFER FORMAT

C = CASSETTE
 UV = UV TAPE
 WAFER RING
 NT = NON UV TAPE
 WAFER RING
 GP = GEL-PAK

TopLine[®]

TITLE FC4356G15C200-DC
 DAISY CHAIN BUMPED DIE

SCALE	SIZE	DRAWING NO.	REV
NONE	A	174356	A

DO NOT SCALE DRAWING

SHEET 7 OF 7